

J1017 U.S. PTO

10/042271



11/11/02

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U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10042271	01/11/2002	451	41	3723	MCDONALD D. NGUYEN

**APPLICANTS: Yoshida Masato; Ashizawa Toranosuke; Terazaki Hiroki; Ootuki Yuuto;
Kurata Yasushi; Matsuzawa Jun; Tanno Kiyohito;

**CONTINUING DATA VERIFIED:

THIS APPLICATION IS A CON OF 09/581,814 09/08/2000 PAT 6,343,976 *

(*) Data inconsistent with PTO records.

** FOREIGN APPLICATIONS VERIFIED:

JAPAN 09-349240 12/18/1997

JAPAN 10-083042 03/30/1998

JAPAN 10-083043 03/30/1998

PG-PUB DO NOT PUBLISH ☐RESCIND ☐Foreign priority claimed ☐ yes ☐ no35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

566.38683CX1

TITLE : Abrasive, method of polishing target member and process for producing semiconductor device

U.S. DEPT. OF COMM. PAT. & TM. PTO-435 (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED	
			Total Claims	Print Claim for O.G.
ISSUE FEE		Primary Examiner	DRAWING	
Amount Due	Date Paid		Sheets Drawg.	Figs. Drawg.
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	Application Examiner	
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